

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

### Product Summary



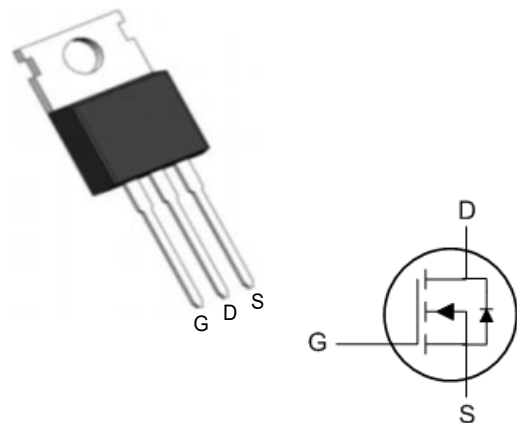
BVDSS	RDSON	ID
70V	5mΩ	80A

### Description

The XR80N07T is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The XR80N07T meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

### TO220AB Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	70	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	80	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	60	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	364	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	400	mJ
$I_{AS}$	Avalanche Current	---	A
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	136	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	---	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	1.1	$^\circ C/W$

### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	0	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	---	---	V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =1A	---	5	6.5	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	G	3	1	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	---	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, T <sub>J</sub> =100°C	---	---	100	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =FV, I <sub>D</sub> =20A	---	H	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	€7	---	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =H V, V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	îî	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	Fî	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	œ	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>GS</sub> =10V, V <sub>DD</sub> =H V, R <sub>G</sub> =1 Ω	---	14.î	---	ns
T <sub>r</sub>	Rise Time		---	H€	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	íJ€	---	
T <sub>f</sub>	Fall Time		---	F2	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =H V, V <sub>GS</sub> =0V, f=1MHz	---	4723	---	pF
C <sub>oss</sub>	Output Capacitance		---	225	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	207	---	

### Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	ì€	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25C	---	---	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =20A, di/dt=100A/μs,	---	GJ	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> =25C	---	Hí	---	nC

**Note :**

F The data is tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

G The data is tested by pulsed pulse width is 300us duty cycle is 2%

H The EAS data shows Max. Rating The test condition is V<sub>GS</sub>=0, V<sub>DD</sub>=40V, V<sub>G</sub>=10V, R<sub>G</sub>=25Ω, L=0.5mH.

I The power dissipation is limited by 50 °C junction temperature

ì The data is theoretically the same as I<sub>DM</sub> and I<sub>DM(A)</sub> in real applications should be limited by total power dissipation.

### Typical Electrical And Thermal Characteristics (Curves)

Figure 1. Output Characteristics

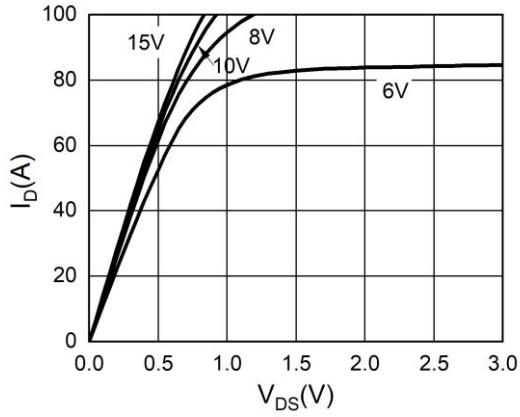


Figure 2. Transfer Characteristics

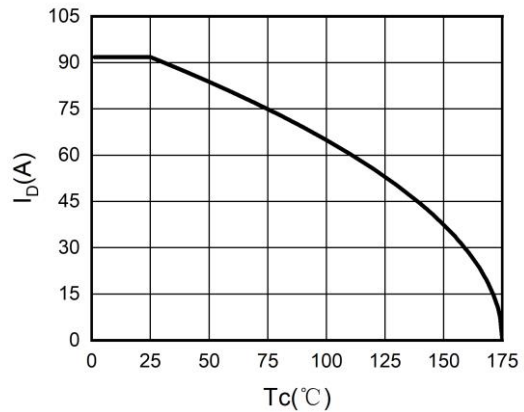
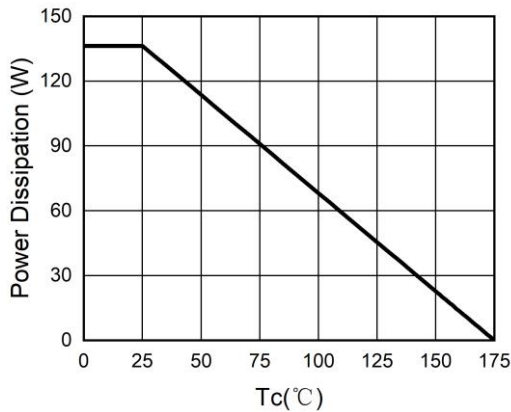
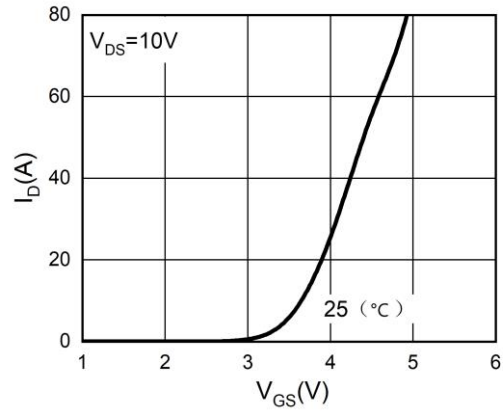


Figure 5.  $BV_{DSS}$  vs Junction Temperature

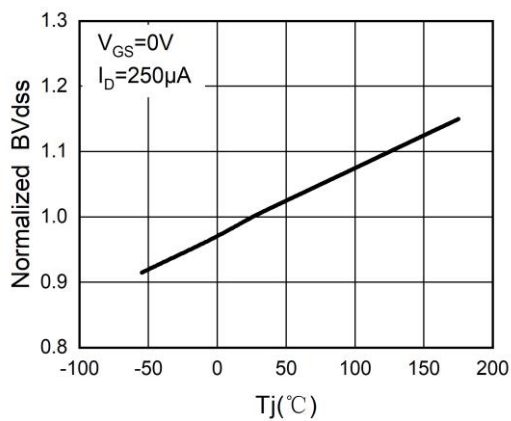
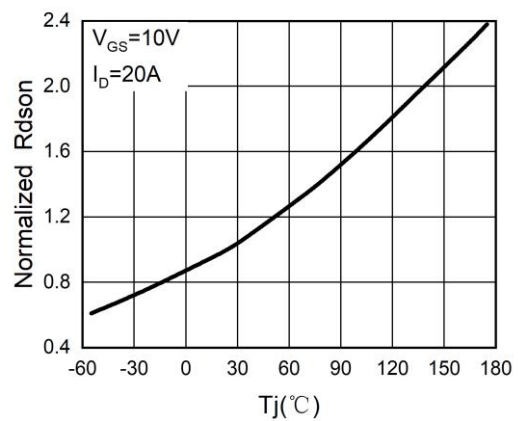
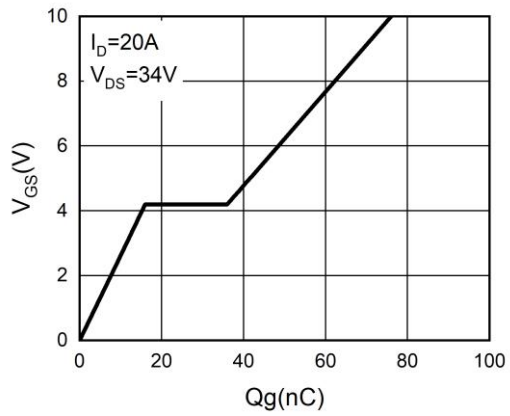


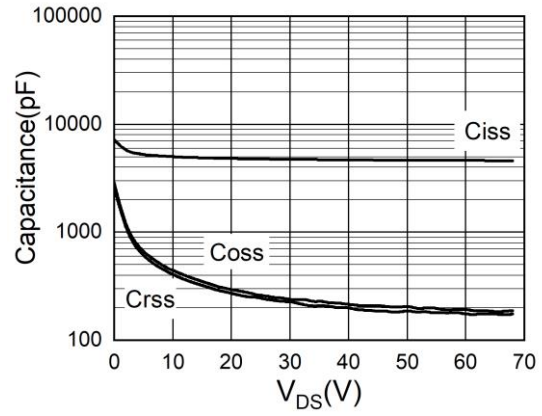
Figure 6.  $R_{DS(ON)}$  vs Junction Temperature



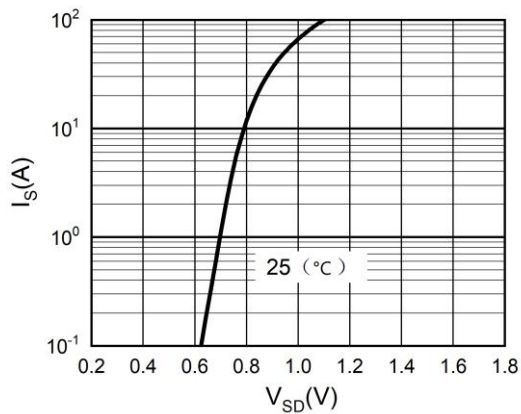
**Figure 7. Gate Charge Waveforms**



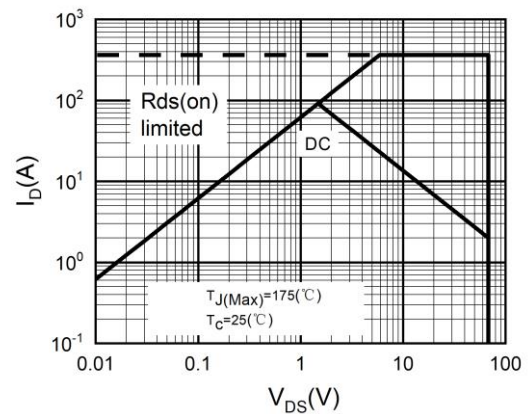
**Figure 8. Capacitance**



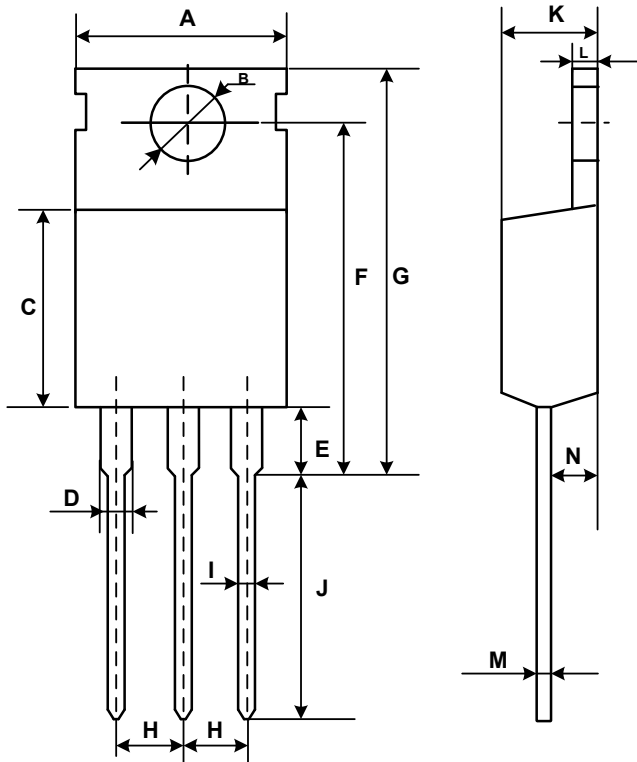
**Figure 9. Body-Diode Characteristics**



**Figure 10. Maximum Safe Operating Area**



### Mechanical Dimensions for TO-220



### COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	9.70	10.30
B	3.40	3.80
C	8.80	9.40
D	1.17	1.47
E	2.60	3.50
F	15.10	16.70
G	19.55MAX	
H	2.54REF	
I	0.70	0.95
J	9.35	11.00
K	4.30	4.77
L	1.20	1.45
M	0.40	0.65
N	2.20	2.60